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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: [info@chipsmall.com](mailto:info@chipsmall.com) Web: [www.chipsmall.com](http://www.chipsmall.com)

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

# 2SD0592 (2SD592)

## Silicon NPN epitaxial planar type

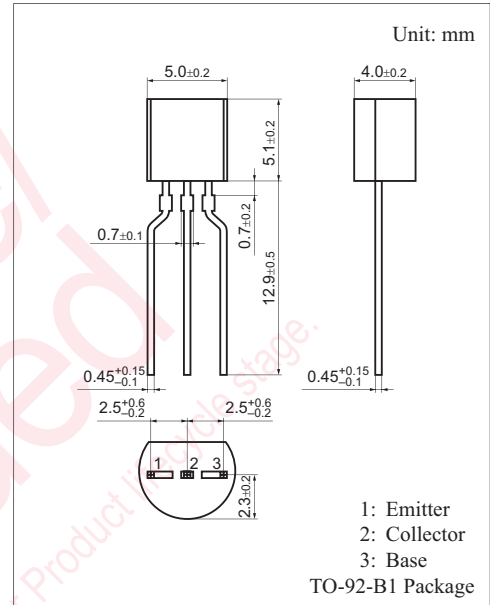
For low frequency amplification  
Complementary to 2SB0621 (2SB621)

### ■ Features

- Large collector power dissipation  $P_C$
- Low collector-emitter saturation voltage  $V_{CE(sat)}$

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	30	V
Collector-emitter voltage (Base open)	$V_{CEO}$	25	V
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V
Collector current	$I_C$	1	A
Peak collector current	$I_{CP}$	1.5	A
Collector power dissipation	$P_C$	750	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$



### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

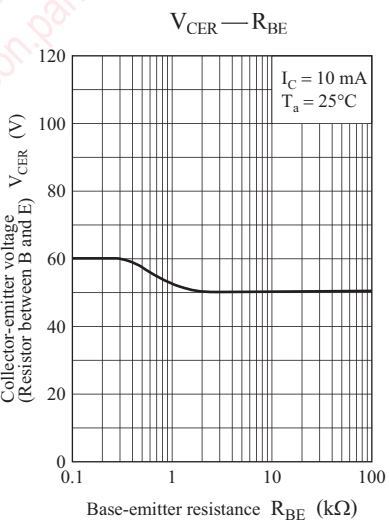
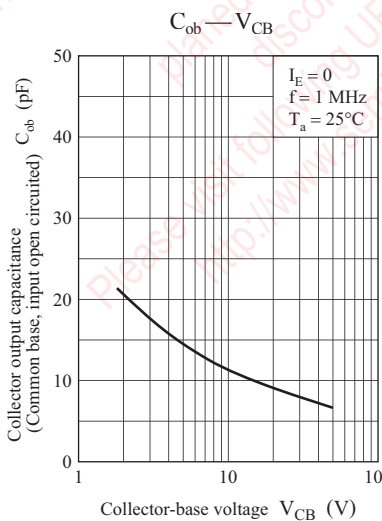
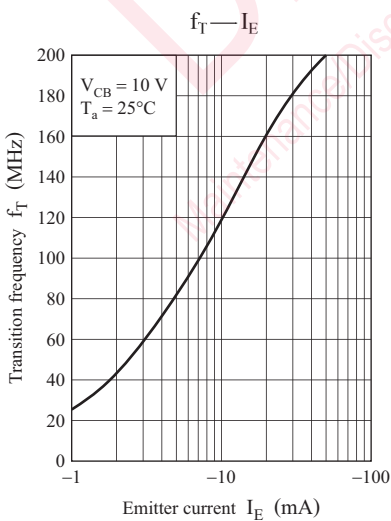
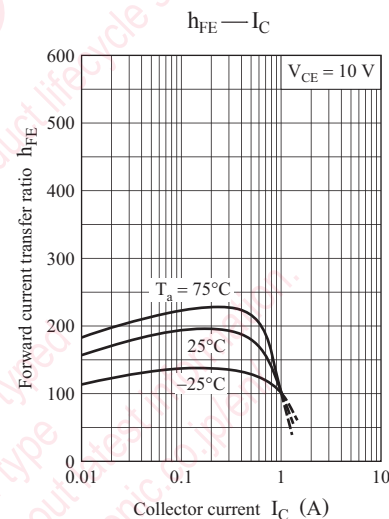
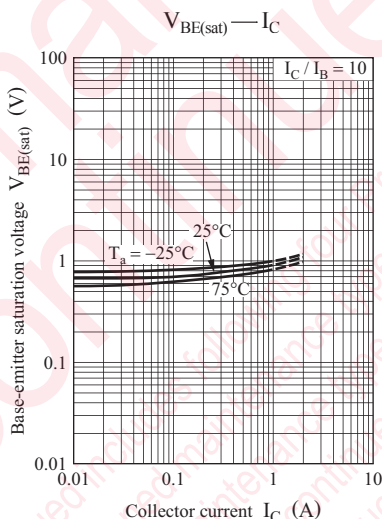
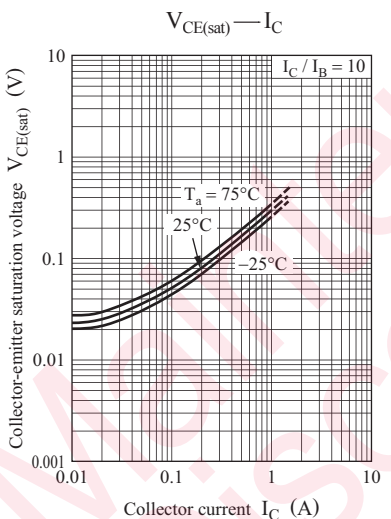
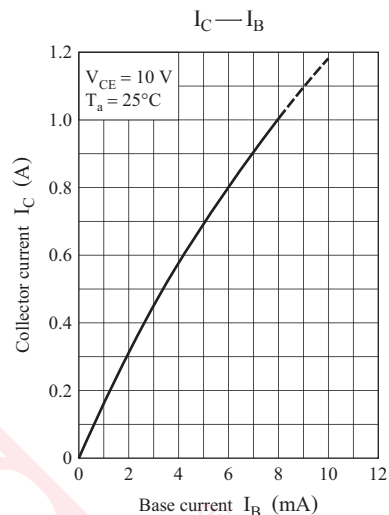
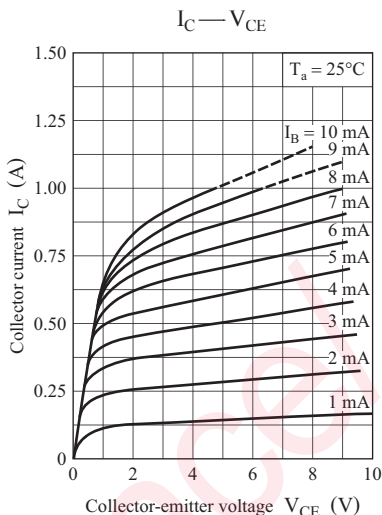
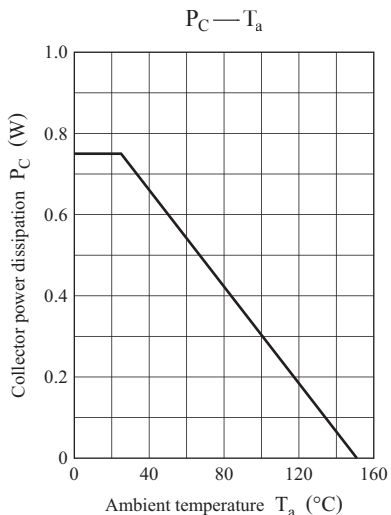
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = 10 \mu\text{A}, I_E = 0$	30			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = 2 \text{ mA}, I_B = 0$	25			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu\text{A}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_E = 0$			0.1	$\mu\text{A}$
Forward current transfer ratio	$h_{FE1}^*$	$V_{CE} = 10 \text{ V}, I_C = 500 \text{ mA}$	85		340	—
	$h_{FE2}$	$V_{CE} = 5 \text{ V}, I_C = 1 \text{ A}$	50			—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.2	0.4	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.85	1.2	V
Collector output capacitance (Common base, input open circuited)	$C_{ob}$	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			20	pF
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz

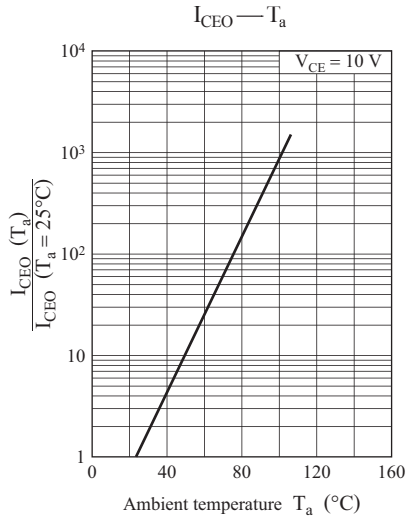
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \* : Rank classification

Rank	Q	R	S
$h_{FE1}$	85 to 170	120 to 240	170 to 340

Note) The part number in the parenthesis shows conventional part number.





Maintenance/Discontinued

Maintenance/Discontinued includes following four Product lifecycle stage.  
planned maintenance type  
maintenance type  
planned discontinued type  
discontinued type  
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